muRata

Reference Specification

DEH Series

High Temperature Low Loss Lead Type Disc Ceramic Capacitors of class 2 for General Purpose

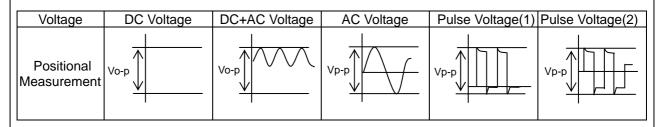
Product specifications in this catalog are as of Dec. 2017, and are subject to change or obsolescence without notice.

Please consult the approval sheet before ordering.Please read rating and Cautions first.

1. OPERATING VOLTAGE

When DC-rated capacitors are to be used in AC or ripple current circuits, be sure to maintain the Vp-p value of the applied voltage or the Vo-p which contains DC bias within the rated voltage range. When the voltage is started to apply to the circuit or it is stopped applying, the irregular voltage may be generated for a transit period because of resonance or switching. Be sure to use a capacitor within rated voltage containing these irregular voltage.

When DC-rated capacitors are to be used in input circuits from commercial power source (AC filter), be sure to use Safety Recognized Capacitors because various regulations on withstand voltage or impulse withstand established for each equipment should be taken into considerations.



2. OPERATING TEMPERATURE AND SELF-GENERATED HEAT

Keep the surface temperature of a capacitor below the upper limit of its rated operating temperature range. Be sure to take into account the heat generated by the capacitor itself.

When the capacitor is used in a high-frequency current, pulse current or the like, it may have the selfgenerated heat due to dielectric-loss. The allowable frequency should be in less than 300kHz in sine wave. Applied voltage should be the load such as self-generated heat is within 20 °C <u>on the condition of atmosphere temperature 25 °C.</u> When measuring, use a thermocouple of small thermal capacity-K of ϕ 0.1mm and be in the condition where capacitor is not affected by radiant heat of other components and wind of surroundings. (Never attempt to perform measurement with the cooling fan running. Otherwise, accurate measurement cannot be ensured.)

3. FAIL-SAFE

When capacitor would be broken, failure may result in a short circuit. Be sure to provide an appropriate fail-safe function like a fuse on your product if failure would follow an electric shock, fire or fume.

4. LOAD REDUCTION AND SELF-GENERATED HEAT DURING APPLICATION OF HIGH-FREQUENCY AND HIGH-VOLTAGE

Since the heat generated by the low-dissipation capacitor itself is low, its allowable power is much higher than the general B characteristic. However, in case such an applied load that the self-heating temperature is 20 °C at the rated voltage, the allowable power may be exceeded.

Therefore, when using the low-dissipation capacitors in a high-frequency and high-voltage circuit with a frequency of 1kHz or higher, make sure that the Vp-p values including the DC bias, do not exceed the applied voltage value specified in Table 1. Also make sure that the self-heating temperature (the difference between the capacitor's surface temperature and the capacitor's ambient temperature) at an ambient temperature of 25 °C does not exceed the value specified in Table 1.

As shown in Fig. 2, the self-heating temperature depends on the ambient temperature. Therefore, if you are not able to set the ambient temperature to approximately 25 °C, please contact our sales representatives or product engineers.

Temp.	DC Rated	Allowable Condi	Capacitor's		
Char.	Voltage	Applied Voltage Self-heating Temp.		Ambient	
	· ·····g·	(max.)	(25 °C Ambient Temp.) *1	Temp. *2	
R	250V	250Vp-p	10 °C max.		
С	500V	500Vp-p	20 °C max.		
	1kV	800Vp-p	20 °C max.		
	IKV	1000Vp-p	5 °C max.	-25 to +85 °C	
R	2kV	1400Vp-p	20 °C max.	-25 10 +65 °C	
ĸ		2000Vp-p	5 °C max.		
		1600Vp-p	20 °C max.		
	3.15kV	3150Vp-p	5 °C max.		

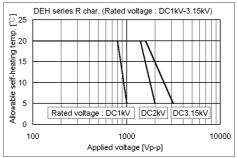
<Table 1> Allowable Conditions at High-frequency

*1 Fig. 1 shows the relationship between the applied voltage and the allowable self-heating temperature regarding 1 to 3.15kV rated voltage of the DEH series R characteristic.

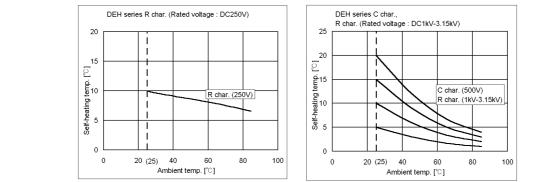
*2 When the ambient temperature is 85 to 125 °C, the applied voltage needs to be further reduced. If the low-dissipation capacitors needs to be used at an ambient temperature of 85 to 125 °C, please contact our sales representatives or product engineers.

*3 Fig. 3 shows reference data on the allowable voltage-frequency characteristic for a sine wave voltage.

<Fig. 1> Relationship Between Applied Voltage and Self-heating Temperature [Allowable Self-heating Temp. at 25 °C Ambient Temp.]

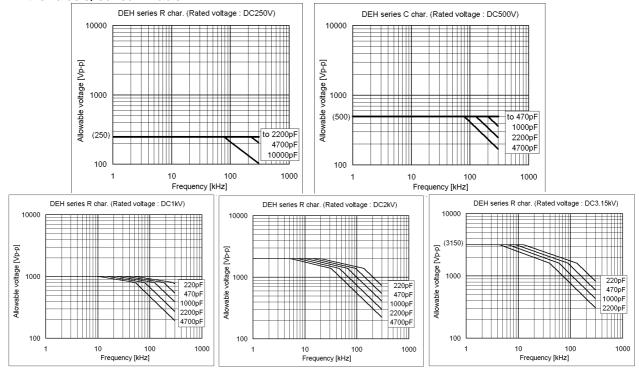


<Fig. 2> Dependence of Self-heating Temperature on Ambient Temperature



<Fig. 3> Allowable Voltage (Sine Wave Voltage) – Frequency Characteristic [At Ambient Temperature of 85 °C or less]

Because of the influence of harmonics, when the applied voltage is a rectangular wave or pulse wave voltage (instead of a sine wave voltage), the heat generated by the capacitor is higher than the value obtained by application of the sine wave with the same fundamental frequency. Roughly calculated for reference, the allowable voltage for a rectangular wave or pulse wave corresponds approximately to the allowable voltage for a sine wave whose fundamental frequency is twice as large as that of the rectangular wave or pulse wave. This allowable voltage, however, varies depending on the voltage and current waveforms. Therefore, you are requested to make sure that the self-heating temperature is not higher than the value specified in Table 1.



5. VIBRATION AND IMPACT

Do not expose a capacitor or its leads to excessive shock or vibration during use.

6. SOLDERING

When soldering this product to a PCB/PWB, do not exceed the solder heat resistance specification of the capacitor. Subjecting this product to excessive heating could melt the internal junction solder and may result in thermal shocks that can crack the ceramic element.

When soldering capacitor with a soldering iron, it should be performed in following conditions.

Temperature of iron tip : 400 °C max.

Soldering iron wattage : 50W max.

Soldering time : 3.5 s max.

7. BONDING, RESIN MOLDING AND COATING

In case of bonding, molding or coating this product, verify that these processes do not affect the quality of capacitor by testing the performance of the bonded, molded or coated product in the intended equipment.

In case of the amount of applications, dryness / hardening conditions of adhesives and molding resins containing organic solvents (ethyl acetate, methyl ethyl ketone, toluene, etc.) are unsuitable, the outer coating resin of a capacitor is damaged by the organic solvents and it may result, worst case, in a short circuit.

The variation in thickness of adhesive, molding resin or coating may cause a outer coating resin cracking and/or ceramic element cracking of a capacitor in a temperature cycling.

8. TREATMENT AFTER BONDING, RESIN MOLDING AND COATING

When the outer coating is hot (over 100 $^{\circ}$ C) after soldering, it becomes soft and fragile. So please be careful not to give it mechanical stress.

Failure to follow the above cautions may result, worst case, in a short circuit and cause fuming or partial dispersion when the product is used.

9. OPERATING AND STORAGE ENVIRONMENT

The insulating coating of capacitors does not form a perfect seal; therefore, do not use or store capacitors in a corrosive atmosphere, especially where chloride gas, sulfide gas, acid, alkali, salt or the like are present. And avoid exposure to moisture. Before cleaning, bonding, or molding this product, verify that these processes do not affect product quality by testing the performance of a cleaned, bonded or molded product in the intended equipment. Store the capacitors where the temperature and relative humidity do not exceed -10 to 40 °C and 15 to 85%. Use capacitors within 6 months after delivered. Check the solderability after 6 months or more.

10. LIMITATION OF APPLICATIONS

Please contact us before using our products for the applications listed below which require especially high reliability for the prevention of defects which might directly cause damage to the third party's life, body or property.

- 1. Aircraft equipment
- 2. Aerospace equipment
- 3. Undersea equipment
- 4. Power plant control equipment
- 5. Medical equipment
- 6. Transportation equipment (vehicles, trains, ships, etc.)
- 7. Traffic signal equipment
- 8. Disaster prevention / crime prevention equipment
- 9. Data-processing equipment exerting influence on public
- 10. Application of similar complexity and/or reliability requirements to the applications listed in the above.

NOTICE

1. CLEANING (ULTRASONIC CLEANING)

To perform ultrasonic cleaning, observe the following conditions. Rinse bath capacity : Output of 20 watts per liter or less. Rinsing time : 5 min maximum.

Do not vibrate the PCB/PWB directly.

Excessive ultrasonic cleaning may lead to fatigue destruction of the lead wires.

2. CAPACITANCE CHANGE OF CAPACITORS

- Class 1 capacitors

Capacitance might change a little depending on a surrounding temperature or an applied voltage. Please contact us if you use for the strict time constant circuit.

Class 2 and 3 capacitors

Class 2 and 3 capacitors like temperature characteristic B, E and F have an aging characteristic, whereby the capacitor continually decreases its capacitance slightly if the capacitor leaves for a long time. Moreover, capacitance might change greatly depending on a surrounding temperature or an applied voltage. So, it is not likely to be able to use for the time constant circuit. Please contact us if you need a detail information.

- 1.Please make sure that your product has been evaluated in view of your specifications with our product being mounted to your product.
- 2. You are requested not to use our product deviating from this specification.

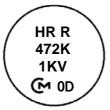
			,		
Class 2 of DEH s	series used for Gene	eral Electric equip comotive power tr	ment.		eramic Capacitors of including battery chargers
2. Rating 2-1. Operating ten -25	nperature range ∼ +125°C				
2-2. Part number	configuration				
ex.) <u>DEH</u> Series	R3 3. Temperature Rate characteristic volta	ed Capacitance	K Capacitance tolerance	<u>B3</u> Lead code	B Packing Individual style code specification
Temperat	ure characteristic				
• Temperat	Code	Temp	erature characte	ristic]
	R3		R	1010	
	C3		C		
Ple	ease confirm detaile	d specification or	[Specification a	nd test	methods].
 Rated vol 	ltage				
	Code		Rated voltage		
	2H		DC500V		
	3A		DC1kV		J
ex.) Ir • Capacita		1700pF	s ; the last digit c	lenotes	the multiplier of 10 in pF.
Lead cod	le				
	Code		Lead style		
	A*		crimp long type		
	B*		crimp short type		
	N*		crimp taping type	e	J
* F	Please refer to [Par	t number list].			
Solde	er coated copper wire	e is applied for te	rmination.		
Packing	style code				_
	Code		Packing type		
	В	Bulk typ			
	A	Ammo	back taping type]
In cas	I specification se part number cann nd of part number.	ot be identified w	ithout 'individual	specific	ation' , it is added at

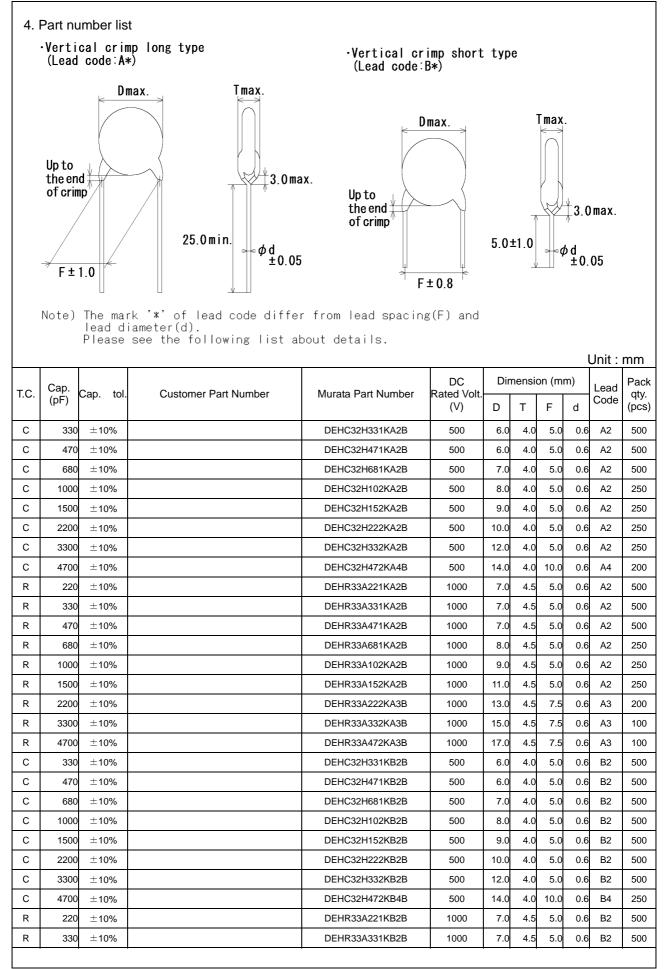
3. Marking

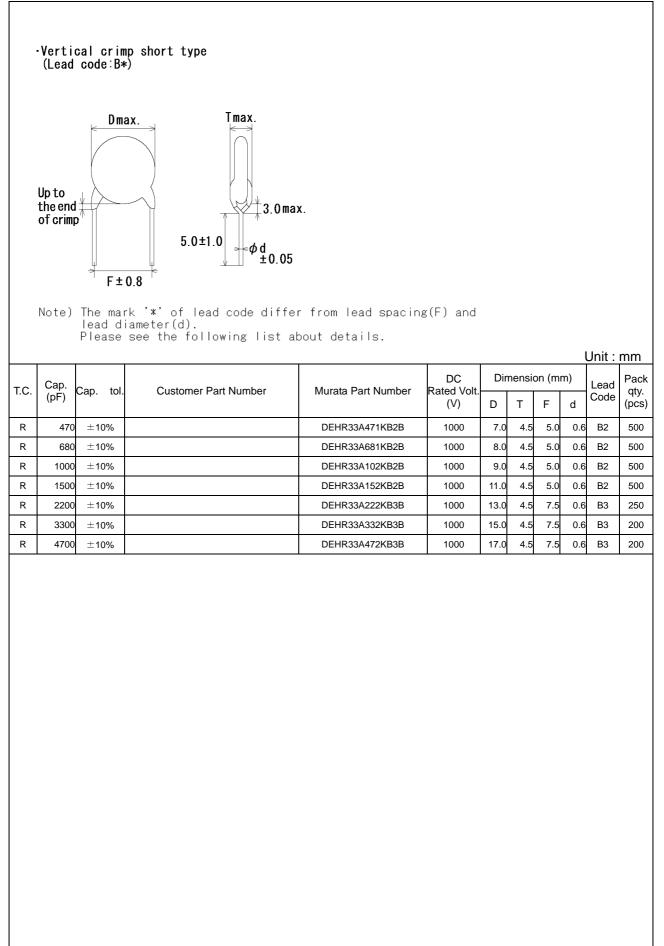
High temperature guaranteed co	ode : HR				
Temperature characteristic	: Letter code (Omitted for maximum body diameter ϕ 6mm				
	and under of char. C)				
Nominal capacitance	: 3 digit system				
Capacitance tolerance	: Code(Omitted for maximum body diameter ϕ 6mm and under)				
Rated voltage	: Letter code (Omitted for the rated voltage DC500V.)				
Company name code	: Abbreviation 🛛 🚱				
	(Omitted for maximum body diameter ϕ 9mm and under)				
Manufacturing year	: Letter code(The last digit of A.D. year.)				
Manufacturing month	: Code				
	ex.) YEAR MONTH				
	201 <u>0</u> 12(December)				
	0D*				
	* From January to September : "1" to "9",				

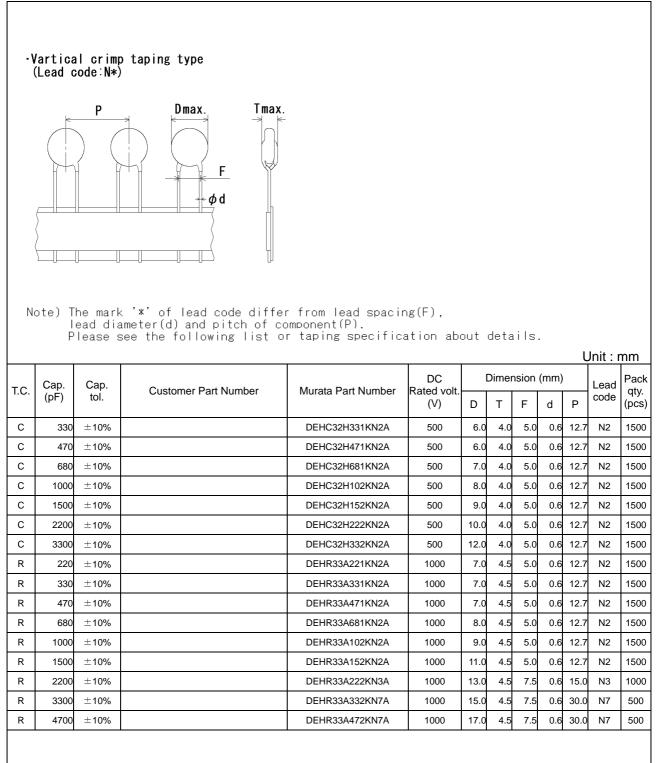
October : "O" , November : "N" , December : "D"

(Example)









Reference only

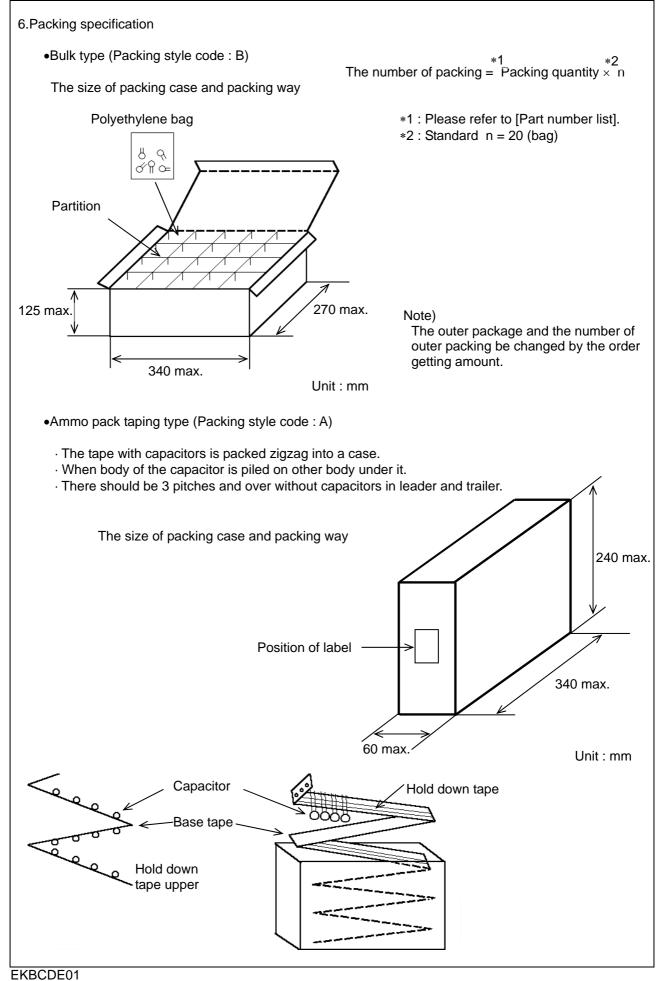
	ecification and test										
No. 1	Ite Appearance and o		Specific No marked defect		2	Test method The capacitor should be inspected by naked eyes					
'			No marked defect on appearance form and dimensions.					nce of def		y nakeu	Cy C S
			Please refer to [P	art number list].	Dimensions should be measured with slide calipers.					
2	Marking		To be easily legib	e.		The capacitor should be inspected by naked eyes.					
3	Dielectric	Between lead wires	No failure.			The capacitor should not be damaged when DC voltage of 200% of the rated voltage (In case of					
	strength	WIIes			rated voltage: DC1kV) or DC voltage						
						rated voltage (In case of rated voltage: applied between the lead wires for 1 to (Charge/Discharge current≤50mA.)					
		Body insulation	No failure.		The capacitor is placed in the contain balls of diameter 1mm so that each le shortcircuited, is kept about 2mm off the balls as shown in the figure, and						
		Insulation						,			
							Y				
								.)<50/60⊦	lz>	Å.	
					is applied for 1 to 5 s between capacitor lead			About 2m			
						wires and small metals.			etal balls		
						(Charge/Discharge current≤50mA.)					
4	Insulation	Between lead	$10000M\Omega$ min.			_			should be		ed with
	Resistance (I.R.)	wires				DC500	D±50V with	nin 60±5 s	s of chargi	ng.	
5	Capacitance		Within specified to	olerance.					e measure	ed at 20°	C with
-	.							C5V(r.m.s			
6	Dissipation Factor	r (D.F.)	Char. R : 0.2% r				•		uld be me		t 20°C
			Char. C : 0.3% r	nax.		with 1	±0.2kHz a	nd AC5V(r.m.s.) ma	X	
7	Temperature char	acteristic		emp. char.					ment shou	uld be m	ade at
			-25 to +85°C R Within ±15%	+85 to +125°C Within +15/-30%		each s	step specif	fied in Tab	ole.		
			C Within ±20%	Within +15/-30%							
			Pre-treatment : C	anacitor should	d h	s stored	at 125+39	C for 1 h	then plac	te he	
				oom condition					•	cuat	
				Step		1	2	3	4	5	
				Temp.(°C)		20+2	-25±3	20±2	4 125±2	20±2	-
				Temp.(C)	4	2012	-23±3	2012	125±2	2012	
8	Strength of lead	Pull	Lead wire should						right, fix th		,,,,,,
			Capacitor should	not be broken.	•				apply a te ead wire ir		Цтų
									acitor up to		Ъ
								for 10±1 :			w
		Bending	_			Each I	and wire a	should bo	subjected	to 5N of	woight
		Benuing							of egress,		
									al position,		
									he rate of		
						in 2 to					
*	¹ "room condition" T	Temperature: 15 to	o 35°C, Relative hur	nidity: 45 to 75	%,	Atmoon	heric pres	sure: 86 t	o 106kPa		
						Aunospi					
						Atmosp					
						Atmosp					
						Almospi					
						Atmospi					
						Atmospi					
						Ainospi					
						Ainospi					
						Ainospi					
						Almospi					
						Annospi					
						Aunospi					
						Ашор					
						Ашор					
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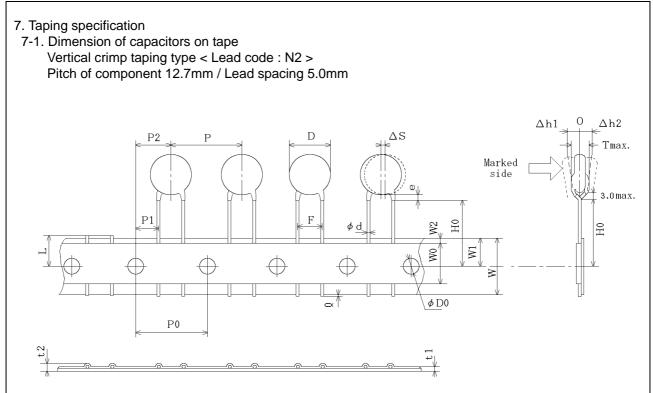
Reference only

			Reference only	
No.	lte		Specification	Test method
9	Vibration resistance	Appearance Capacitance D.F.	No marked defect.Within specified tolerance.Char. R : 0.2% max.Char. C : 0.3% max.	The capacitor should be firmly soldered to the supporting lead wire and vibrated at a frequency range of 10 to 55Hz, 1.5mm in total amplitude, with about a 1min rate of vibration change from 10Hz to 55Hz and back to 10Hz. Apply for a total of 6 h;
10	Solderability of lea	ads	Lead wire should be soldered with uniformly coated on the axial direction over 3/4 of the circumferential direction.	2 h each in 3 mutually perpendicular directions. The lead wire of a capacitor should be dipped into a ethanol solution of 25wt% rosin and then into molten solder for 2±0.5 s. In both cases the depth of dipping is up to about 1.5 to 2mm from the root of lead wires. Temp. of solder : 245±5°C Lead Free Solder (Sn-3Ag-0.5Cu)
		Ι.		235±5°C H63 Eutectic Solder
11	Soldering effect (Non-preheat)	Appearance Capacitance change Dielectric strength (Between lead wires)	No marked defect. Within ± 10% Per item 3.	The lead wire should be immersed into the melted solder of 350±10°C up to about 1.5 to 2.0mm from the main body for 3.5±0.5 s. Pre-treatment : Capacitor should be stored at 125±3°C for 1 h, then placed at *1room condition for 24±2 h before initial measurements. Post-treatment : Capacitor should be stored for 24±2 h at *1room condition.
12	Soldering effect (On-preheat)	Appearance Capacitance change Dielectric strength (Between lead wires)	No marked defect. Within ± 10% Per item 3.	First the capacitor should be stored at 120+0/-5°C for 60+0/-5 s. Then, as in figure, the lead wires should be immersed solder of 260+0/-5°C up to 1.5 to 2.0mm from the root of terminal for 7.5+0/-1 s. Thermal insulating Capacitor Holten Solder Pre-treatment : Capacitor should be stored at 125±3°C for 1 h, then placed at *1room condition for 24±2 h
13	Humidity (Under steady state)	Appearance Capacitance change D.F.	No marked defect. Within ±10% 0.4% max.	before initial measurements. Post-treatment : Capacitor should be stored for 24±2 h at *1room condition. Set the capacitor for 500 +24/-0 h at 40±2°C in 90 to 95% relative humidity. Pre-treatment : Capacitor should be stored at 125±3°C for 1 h,
		I.R.	1 000MΩ min.	then placed at *1room condition for 24±2 h before initial measurements. Post-treatment : Capacitor should be stored for 1 to 2 h at *1room condition.
		iomperature. 13 l	o 35°C, Relative humidity: 45 to 75%,	

Reference only

<u></u>			Reference only	
<u>No.</u> 14	Ite Humidity loading	m Appearance	Specification No marked defect.	Test method Apply the rated voltage for 500 +24/-0 h at 40±2°C
. 7		Capacitance	Within ±10%	in 90 to 95% relative humidity.
		change		(Charge/Discharge current≤50mA.)
		D.F.	0.6% max.	Pre-treatment :
		I.R.	1 000MΩ min.	Capacitor should be stored at 125±3°C for 1 h,
				then placed at *1room condition for 24 ± 2 h
				before initial measurements.
				Post-treatment :
				Capacitor should be stored for 1 to 2 h at *1room
				condition.
15	Life	Appearance	No marked defect.	Apply a DC voltage of 200% of the rated voltage
		Capacitance	Within ±10%	(In case of rated voltage:DC500V) or DC voltage of
		change	a 19/	150% of the rated voltage (In case of rated
		D.F.	0.4% max.	voltage:DC1kV) for 1000 +48/-0 h at 125±2°C and
		I.R.	2000M Ω min.	relative humidity of 50% max
				(Charge/Discharge current≤50mA.) Pre-treatment :
				Capacitor should be stored at $125\pm3^{\circ}$ C for 1 h,
				then placed at *1room condition for 24±2 h before initial measurements.
				Post-treatment :
				Capacitor should be stored at 125±3°C for 1 h, the
				placed at *1room condition for 24 ± 2 h.
16	Temporatura	Appearance	No marked defect	The capacitor should be subjected to 5 temperature
10	Temperature cycle	Appearance Capacitance	No marked defect. Within ±10%	The capacitor should be subjected to 5 temperature cycles.
	Cycle	change		<pre></pre>
		D.F.	0.4% max.	
		I.R.		Step Temperature(°C) Time
			1000MΩ min.	130 min
		Dielectric	Per item 3.	2 Room Temp. 3 min
		strength (Between lead		3 +125±3 30 min
		wires)		4 Room Temp. 3 min
		wires)		Cycle time : 5 cycle
				Pre-treatment :
				Capacitor should be stored at 125±3°C for 1 h,
				then placed at *1room condition for 24±2 h
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				before initial measurements. Post-treatment :
				before initial measurements. Post-treatment : Capacitor should be stored for 24±2 h at *1room
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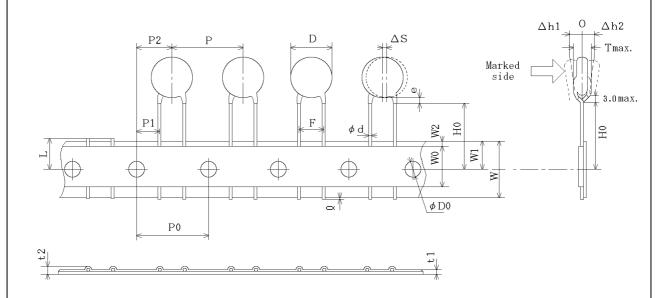




Unit : mm

ltem	Code	Dimensions	Remarks	
Pitch of component	Р	12.7±1.0		
Pitch of sprocket hole	P0	12.7±0.3		
Lead spacing	F	0.8 5.0±0.2		
Length from hole center to component center	P2	6.35±1.3		
Length from hole center to lead	P1	3.85±0.7	Deviation of progress direction	
Body diameter	D	Please refer to [P	art number list].	
Deviation along tape, left or right	ΔS	0±1.0	They include deviation by lead bend .	
Carrier tape width	W	18.0±0.5		
Position of sprocket hole	W1	9.0±0.5	Deviation of tape width direction	
Lead distance between reference and bottom planes	HO	$18.0\pm^{2.0}_{0}$		
Protrusion length	Q	+0.5~-1.0		
Diameter of sprocket hole	φD0	4.0±0.1		
Lead diameter	φd	0.60±0.05		
Total tape thickness	t1	0.6±0.3	<u>_</u>	
Total thickness, tape and lead wire	t2	1.5 max.	They include hold down tape thickness	
Deviation across tape, front	∆h1	1.0		
Deviation across tape, rear	∆h2	1.0 max.		
Portion to cut in case of defect	L	11.0± ⁰ _{1.0}		
Hold down tape width	W0	11.5 min.		
Hold down tape position	W2	1.5±1.5		
Coating extension on lead	е	Up to the end of c	rimp	
Body thickness	Т	Please refer to [P	art number list].	

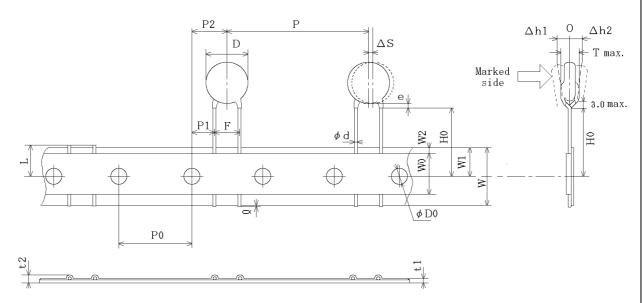
Vertical crimp taping type < Lead code : N3 > Pitch of component 15.0mm / Lead spacing 7.5mm



			Unit : mm
Item	Code	Dimensions	Remarks
Pitch of component	Р	15.0±2.0	
Pitch of sprocket hole	P0	15.0±0.3	
Lead spacing	F	7.5±1.0	
Length from hole center to component center	P2	7.5±1.5	
Length from hole center to lead	P1	3.75±1.0	Deviation of progress direction
Body diameter	D	Please refer to [Part number list].
Deviation along tape, left or right	ΔS	0±2.0	They include deviation by lead bend .
Carrier tape width	W	18.0±0.5	
Position of sprocket hole	W1	9.0±0.5	Deviation of tape width direction
Lead distance between reference and bottom planes	H0	$18.0\pm^{2.0}_{0}$	
Protrusion length	Q	+0.5~-1.0	
Diameter of sprocket hole	φD0	4.0±0.1	
Lead diameter	φd	0.60±0.05	
Total tape thickness	t1	0.6±0.3	
Total thickness, tape and lead wire	t2	1.5 max.	They include hold down tape thickness.
Deviation across tape, front	∆h1	0.0	
Deviation across tape, rear	∆h2	2.0 max.	
Portion to cut in case of defect	L	11.0 ± ⁰ _{1.0}	
Hold down tape width	W0	11.5 min.	
Hold down tape position	W2	1.5±1.5	
Coating extension on lead	е	Up to the end of	crimp
Body thickness	Т	Please refer to [Part number list].

Vertical crimp taping type < Lead code : N7 > Pitch of component 30.0mm /Lead spacing 7.5mm

Item



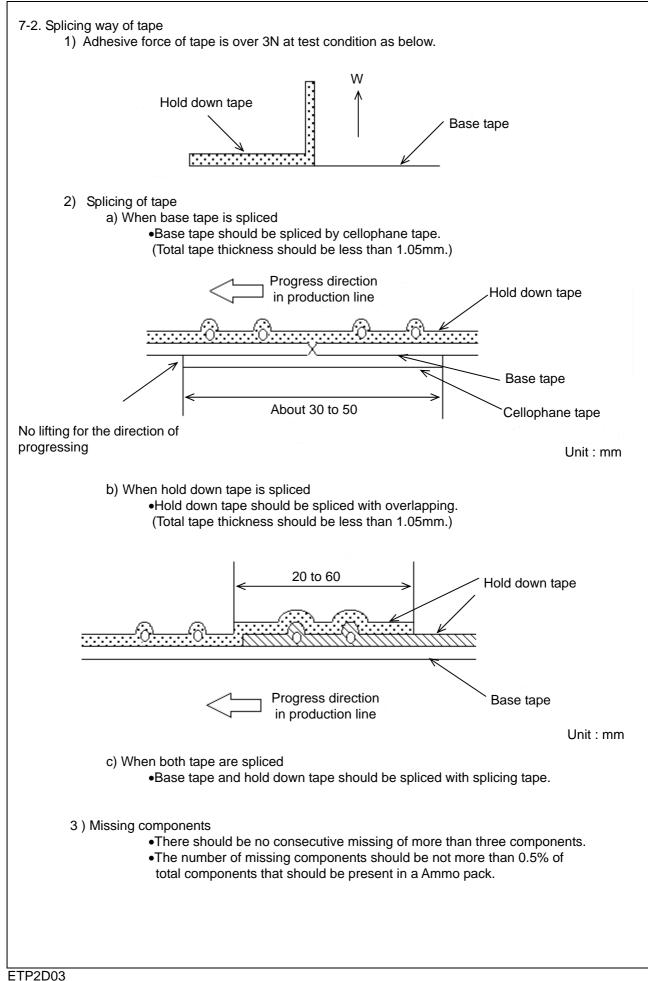
Dimensions

Code

Remarks

Unit : mm

Rom	oouc	Billionolono	rtomanto	
Pitch of component	Р	30.0±2.0		
Pitch of sprocket hole	P0	15.0±0.3		
Lead spacing	F	7.5±1.0		
Length from hole center to component center	P2	7.5±1.5		
Length from hole center to lead	P1	3.75±1.0	Deviation of progress direction	
Body diameter	D	Please refer to [Part number list].	
Deviation along tape, left or right	ΔS	0±2.0	They include deviation by lead bend.	
Carrier tape width	W	18.0±0.5		
Position of sprocket hole	W1	9.0±0.5	Deviation of tape width direction	
Lead distance between reference and bottom	но	$18.0\pm^{2.0}_{0}$		
planes		10.0-0		
Protrusion length	Q	+0.5~-1.0		
Diameter of sprocket hole	φD0	4.0±0.1		
Lead diameter	φd	0.60±0.05		
Total tape thickness	t1	0.6±0.3	They include held down tone thickness	
Total thickness, tape and lead wire	t2	1.5 max.	They include hold down tape thickness	
Deviation across tape, front	∆h1	2.0 max.		
Deviation across tape, rear	∆h2			
Portion to cut in case of defect	L	11.0 ± ⁰ _{1.0}		
Hold down tape width	W0	11.5 min.		
Hold down tape position	W2	1.5±1.5		
Coating extension on lead	е	Up to the end of	crimp	
Body thickness	Т	Please refer to [Part number list].		



This products of the following crresponds to EU RoHS 当製品は以下の欧州RoHSに対応しています。

(1) RoHS

EU RoHs 2011/65/EC compliance 2011/65/EC(改正RoHS指令)に対応

maximum concentration values tolerated by weight in homogeneous materials

1000 ppm maximum Lead

1000 ppm maximum Mercury

•100 ppm maximum Cadmium

•1000 ppm maximum Hexavalent chromium

•1000 ppm maximum Polybrominated biphenyls (PBB)

•1000 ppm maximum Polybrominated diphenyl ethers (PBDE)

Mouser Electronics

Authorized Distributor

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Murata:

DEHC32H222KA2B DEHR33A152KA2B DEHC32H331KA2B DEHC32H681KA2B DEHC32H332KA2B
DEHC32H102KA2B DEHC32H152KA2B DEHR33A472KA4B DEHR33A472KA3B DEHR33A222KA3B
DEHR33A222KA4B DEHR33A331KA2B DEHR33A471KN2A DEHR33A221KN2A DEHC32H102KN2A
DEHC32H471KB2B DEHR33A102KN2A DEHR33A681KN2A DEHR33A102KA2B DEHR33A221KEAB
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DEHR33A332KEBB DEHR33A471KA2B DEHC32H471KA2B DEHC32H102KB2B DEHC32H152KB2B
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DEHR33A222KN3A DEHR33A331KB2B DEHR33A332KB3B DEHR33A332KN7A DEHR33A471KB2B
DEHR33A472KB3B DEHR33A472KN7A DEHR33A681KB2B DEHR33A331KN2A